1. A bond pad assembly comprising:

a bond pad;

a trace coupled to said pad and extending away from said pad in a first direction; and

a trace stub coupled to said pad and extending away from said pad in a direction other than said first direction.

2. The assembly of claim 1 wherein said stub extends diametrically away from said trace.

3. The assembly of claim 1 wherein said bond pad is a non-solder mask defined pad.

4. The assembly of claim 1 wherein said stub has a thickness and width substantially equal to the thickness and width of said trace.

5. The assembly of claim 1 including a solder mask which defines a solder receiving area proximate to said bond pad.

6. The assembly of claim 5 wherein said stub extends outwardly into said solder mask.

7. The assembly of claim 1 including a set of three stubs each oriented 90° away from one of the other of said stubs, one of said stubs being diametrically opposed to said trace.

8. The assembly of claim 1 wherein said bond pad includes a tear-drop shaped portion coupling said bond pad to said trace, said stub also being tear-drop shaped.

9. The assembly of claim 1 wherein said bond pad is adapted to receive a solder ball.

10. A bonding system comprising:

a bond pad;

a trace coupled to said bond pad and extending away from said pad; and

an element adapted to counteract the attractive forces applied by the trace to solder placed on the bond pad.

11. The system of claim 10 wherein said element includes a trace-like portion extending away from said bond pad in a direction opposite to the direction that said trace extends away from said bond pad.

12. The system of claim 11 wherein said trace-like element has the width and thickness of said trace.

13. The system of claim 10 wherein said bond pad is coupled to said trace by a tear-drop shaped portion, said element including a tear-drop shaped portion.

14. The system of claim 10 including a solder mask defining a solder mask opening around said bond pad, said element extending from said bond pad and through said opening.

15. The system of claim 10 including a solder mask and an opening defined in said solder mask surrounding said bond pad wherein said element does not extend across said solder mask opening.

16. The system of claim 10 wherein the attractive forces applied to said solder ball arise from the configuration of said trace, said element adapted to emulate said trace.

17. The system of claim 10 including a solder mask surrounding said bond pad, the attractive force on said solder being the result of the effects of the edge of said

solder mask, said solder mask edge being arranged to create a counteractive force on said solder.

18. The system of claim 17 wherein said solder mask includes a plurality of symmetrically disposed lobes.

19. The system of claim 10 wherein said element is configured symmetrically to said trace.

20. The system of claim 10 further including a device adapted to center the solder against forces which act transversely to the length of said trace.

21. The system of claim 20 including a stub trace which extends away from said bond pad in opposition to said trace and a pair of stub traces oriented at 90° to said trace and coupled to said bond pad.

22. A method of positioning solder on bond pads coupled to traces, said bond pads being surrounded by solder mask material, said method comprising:

depositing solder on a first bond pad having a trace extending in a first direction;

depositing solder on a second bond pad having a trace extending in a second direction, said first and second directions being different; and

causing said solder deposited on said first bond pad to move to a displaced position with respect to said first bond pad, such that said solder aligns with said solder deposited on said second bond pad.

23. The method of claim 22 including nesting said first bond pad with a trace coupled to said second bond pad, and nesting said second bond pad with a trace coupled to said first bond pad.

24. The method of claim 22 wherein causing includes wicking said solder towards a trace coupled to said first bond pad.

25. A method of forming solder connections in integrated circuits comprising:

depositing solder on a bond pad;

counteracting an attractive force supplied by a bond pad trace to the solder by providing a similar and opposite force on the solder.

26. The method of claim 25 wherein counteracting includes forming a trace-like portion which extends away from said bond pad in a direction opposite to the direction that the trace extends away from said bond pad.

27. The method of claim 26 wherein counteracting includes forming a solder mask around said bond pad and causing said trace-like element to extend outwardly from said bond pad into said solder mask.

28. The method of claim 25 wherein counteracting includes forming tear-drop shaped portions on two opposed sides of a bond pad.

29. The method of claim 25 further including providing elements which tend to cause said solder to center on said bond pad.

30. The method of claim 29 further including providing a set of three elements coupled to said bond pad and oriented at approximately 90° to an adjacent element.